

# STGY40NC60VD

### N-channel 600V - 50A - Max247 Very fast PowerMESH™ IGBT

### Features

Туре	V <sub>CES</sub>	V <sub>CE(sat)</sub> (max)@25°C	Ι <sub>C</sub> @100°C
STGY40NC60VD	600V	< 2.5V	50A

- High current capability
- High frequency operation up to 50kHz
- Low C<sub>RES</sub> / C<sub>IES</sub> ratio (no cross-conduction susceptibility)
- Very soft ultra fast recovery antiparallel diode

### Description

Using the latest high voltage technology based on a patented strip layout, STMicroelectronics has designed an advanced family of IGBTs, the PowerMESH<sup>™</sup> IGBTs, with outstanding performances. The suffix "V" identifies a family optimized for very high frequency applications.

### Applications

- High frequency inverters, UPS
- SMPS and PFC in both hard switch and resonant topologies
- Motor drivers

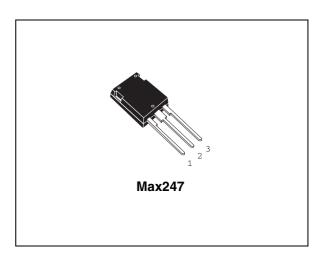
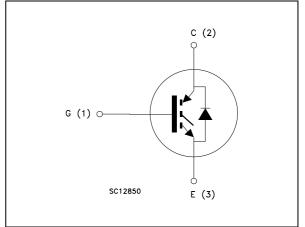


Figure 1. Internal schematic diagram



#### Table 1.Device summary

Order code	Marking	Package	Packaging
STGY40NC60VD	GY40NC60VD	Max247	Tube

## Contents

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## 1 Electrical ratings

Table 1.	Absolute	maximum	ratings

Symbol	Parameter	Value	Unit
V <sub>CES</sub>	Collector-emitter voltage ( $V_{GS} = 0$ )	600	V
I <sub>C</sub> <sup>(1)</sup>	Collector current (continuous) at $T_C = 25^{\circ}C$	80	A
I <sub>C</sub> <sup>(1)</sup>	Collector current (continuous) at T <sub>C</sub> = 100°C	50	A
I <sub>CL</sub> <sup>(2)</sup>	Turn-off SOA minimum current	200	A
١ <sub>F</sub>	Diode RMS forward current at $T_C = 25^{\circ}C$	30	A
V <sub>GE</sub>	Gate-emitter voltage	±20	V
P <sub>TOT</sub>	Total dissipation at $T_{C} = 25^{\circ}C$	260	W
Тj	Operating junction temperature	-55 to 150	°C

1. Calculated according to the iterative formula:

$$I_{C}(T_{C}) = \frac{T_{JMAX} - T_{C}}{R_{THJ - C} \times V_{CESAT(MAX)}(T_{C}, I_{C})}$$

2. Pulse width limited by max junction temperature

Symbol	Parameter	Value	Unit
Rthj-case	Thermal resistance junction-case max IGBT	0.48	°C/W
Rthj-case	Thermal resistance junction-case max diode	1.5	°C/W
Rthj-amb	Thermal resistance junction-ambient max	50	°C/W
TL	Maximum lead temperature for soldering purpose (1.6mm from case, for 10 sec) typ.	300	°C

#### Table 2. Thermal resistance

## 2 Electrical characteristics

(T<sub>CASE</sub>=25°C unless otherwise specified)

Table 3.	Static
	Otatic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V <sub>BR(CES)</sub>	Collector-emitter breakdown voltage	I <sub>C</sub> = 1mA, V <sub>GE</sub> = 0	600			V
V <sub>CE(sat)</sub>	Collector-emitter saturation voltage	V <sub>GE</sub> = 15V, I <sub>C</sub> = 40A V <sub>GE</sub> = 15V, I <sub>C</sub> =40A,Tc=125°C		1.9 1.7	2.5	V V
V <sub>GE(th)</sub>	Gate threshold voltage	$V_{CE} = V_{GE}$ , $I_C = 250 \mu A$	3.75		5.75	V
I <sub>CES</sub>	Collector cut-off current (V <sub>GE</sub> = 0)	V <sub>CE</sub> = Max rating,T <sub>C</sub> = 25°C V <sub>CE</sub> = Max rating,T <sub>C</sub> = 125°C			10 1	μA mA
I <sub>GES</sub>	Gate-emitter leakage current (V <sub>CE</sub> = 0)	$V_{GE}$ = ±20V, $V_{CE}$ = 0			±100	nA
9 <sub>fs</sub>	Forward transconductance	$V_{CE} = 15V_{,} I_{C} = 20A$		20		S

### Table 4. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
C <sub>ies</sub> C <sub>oes</sub> C <sub>res</sub>	Input capacitance Output capacitance Reverse transfer capacitance	V <sub>CE</sub> = 25V, f = 1MHz, V <sub>GE</sub> = 0		4550 350 105		pF pF pF
Q <sub>g</sub> Q <sub>ge</sub> Q <sub>gc</sub>	Total gate charge Gate-emitter charge Gate-collector charge	V <sub>CE</sub> = 390V, I <sub>C</sub> = 40A, V <sub>GE</sub> = 15V, <i>Figure 17</i>		214 30 96		nC nC nC

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t <sub>d(on)</sub> t <sub>r</sub> (di/dt) <sub>on</sub>	Turn-on delay time Current rise time Turn-on current slope	$V_{CC} = 390V, I_C = 40A$ $R_G = 3.3\Omega, V_{GE} = 15V,$ <i>Figure 18, Figure 16</i>		43 17 2060		ns ns A/µs
t <sub>d(on)</sub> t <sub>r</sub> (di/dt) <sub>on</sub>	Turn-on delay time Current rise time Turn-on current slope	$V_{CC} = 390V, I_C = 40A$ $R_G = 3.3\Omega, V_{GE} = 15V,$ $Tj = 125^{\circ}C$ <i>Figure 18, Figure 16</i>		42 19 1900		ns ns A/µs
t <sub>r(Voff)</sub> t <sub>d(Voff)</sub> t <sub>f</sub>	Off voltage rise time Turn-off delay time Current fall time	$V_{CC} = 390V, I_C = 40A$ $R_G = 3.3\Omega, V_{GE} = 15V,$ <i>Figure 18, Figure 16</i>		25 140 45		ns ns ns
t <sub>r(Voff)</sub> t <sub>d(Voff)</sub> t <sub>f</sub>	Off voltage rise time Turn-off delay time Current fall time	$V_{CC} = 390V, I_C = 40A$ $R_G = 3.3\Omega, V_{GE} = 15V,$ $Tj = 125^{\circ}C$ <i>Figure 18, Figure 16</i>		60 170 77		ns ns ns

 Table 5.
 Switching on/off (inductive load)

#### Table 6.Switching energy (inductive load)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
E <sub>on</sub> E <sub>off</sub> <sup>(1)</sup> E <sub>ts</sub>	Turn-on switching losses Turn-off switching losses Total switching losses	$V_{CC} = 390V, I_C = 40A$ $R_G = 3.3\Omega, V_{GE} = 15V,$ <i>Figure 16</i>		330 720 1050	450 970 1420	μJ μJ μJ
E <sub>on</sub> E <sub>off</sub> <sup>(1)</sup> E <sub>ts</sub>	Turn-on switching losses Turn-off switching losses Total switching losses	$V_{CC} = 390V, I_C = 40A$ $R_G = 3.3\Omega V_{GE} = 15V,$ $Tj = 125^{\circ}C$ <i>Figure 16</i>		640 1400 2040		μJ μJ μJ

1. Turn-off losses include also the tail of the collector current



Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V <sub>f</sub>	Forward on-voltage	I <sub>f</sub> = 20A I <sub>f</sub> = 20A, Tj = 125°C		1.5 1	2.2	V V
t <sub>rr</sub> Q <sub>rr</sub> I <sub>rrm</sub>	Reverse recovery time Reverse recovery charge Reverse recovery current	I <sub>f</sub> = 20A,V <sub>R</sub> = 40V, Tj = 25°C, di/dt = 100 A/μs <i>Figure 19</i>		44 66 3		ns nC A
t <sub>rr</sub> Q <sub>rr</sub> I <sub>rrm</sub>	Reverse recovery time Reverse recovery charge Reverse recovery current	I <sub>f</sub> = 40A,V <sub>R</sub> = 50V, Tj =125°C, di/dt = 100A/μs <i>Figure 19</i>		88 237 5.4		ns nC A

 Table 7.
 Collector-emitter diode



### 2.1 Electrical characteristics (curves)

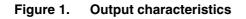
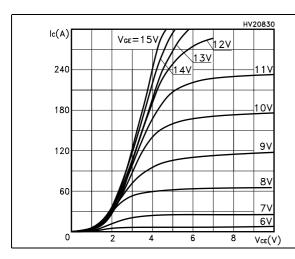
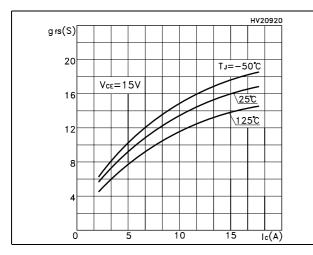


Figure 2. Transfer characteristics







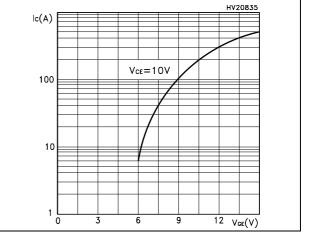
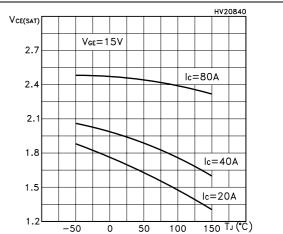
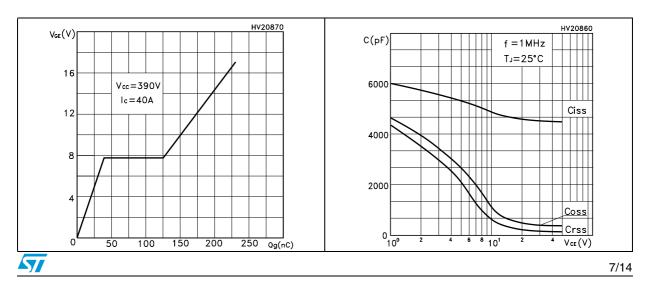


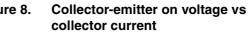
Figure 4. Collector-emitter on voltage vs temperature







## Figure 7. Normalized gate threshold voltage Figure 8. vs temperature



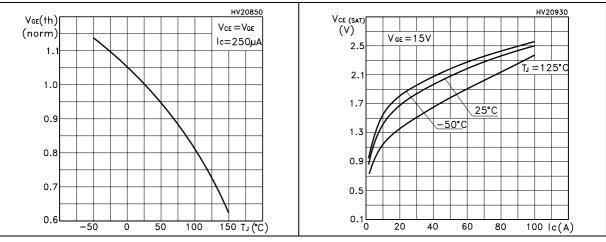


Figure 9. Normalized breakdown voltage vs Figure 10. Switching losses vs temperature temperature

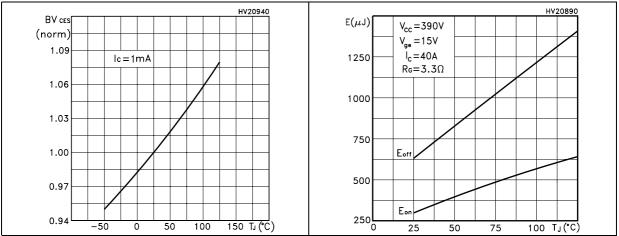
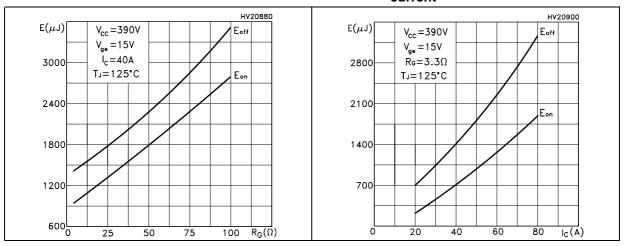


Figure 11. Switching losses vs gate resistance Figure 12. Switching losses vs collector current



#### Figure 13. Turn-off SOA

Figure 14. Thermal impedance

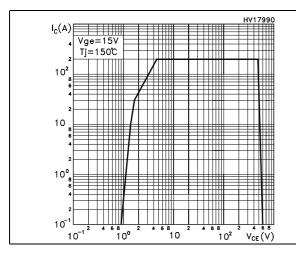
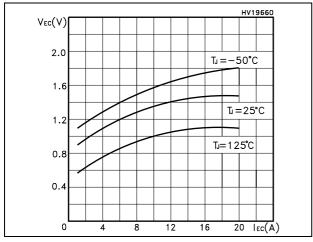
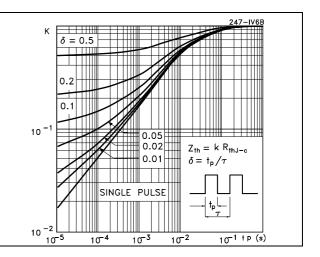


Figure 15. Emitter-collector diode characteristics







## 3 Test circuit

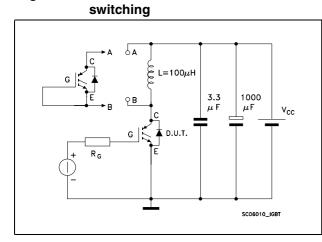
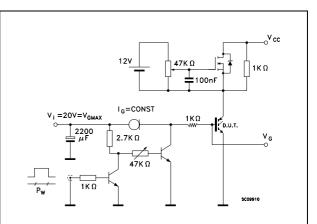
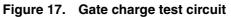


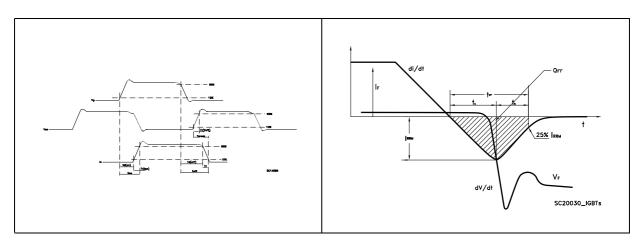
Figure 16. Test circuit for inductive load

Figure 18. Switching waveform









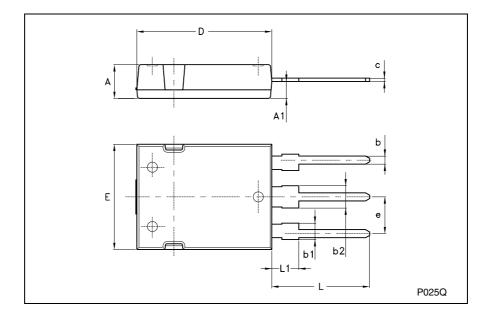


### 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: *www.st.com* 



Max247 MECHANICAL DATA							
DIM.	mm			inch			
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
А	4.70		5.30				
A1	2.20		2.60				
b	1.00		1.40				
b1	2.00		2.40				
b2	3.00		3.40				
с	0.40		0.80				
D	19.70		20.30				
е	5.35		5.55				
Е	15.30		15.90				
L	14.20		15.20				
L1	3.70		4.30				





## 5 Revision history

Date	Revision	Changes	
07-Jun-2004	7	Initial electronic version.	
14-Jul-2004	8	Figure 15 has been update	
13-Jul-2007	9	The document has been reformatted, corrected error on Table 4	



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